

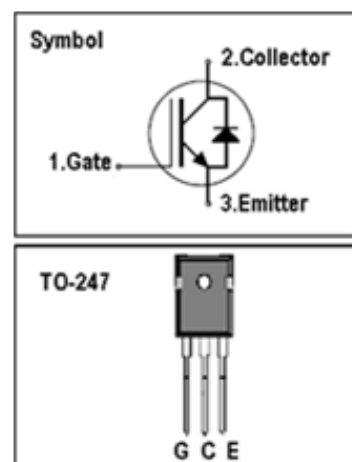
## IGBT

### Features

- 1200V,40A
- $V_{CE(sat)}(typ.)=1.7V@V_{GE}=15V,I_C=40A$
- High speed switching
- Higher system efficiency
- Soft current turn-off waveforms
- Square RBSOA

### General Description

JIAEN Trench IGBTs offer lower losses and higher energy efficiency for application such as UPS, Induction converters, Uninterruptible power supplies and other soft switching applications.



### Absolute Maximum Ratings

Symbol	Parameter	Value	Units
$V_{CES}$	Collector-Emitter Voltage	1200	V
$V_{GES}$	Gate-Emitter Voltage	$\pm 30$	V
$I_C$	Continuous Collector Current ( $T_C=25^\circ C$ )	80	A
	Continuous Collector Current ( $T_C=100^\circ C$ )	40	A
$I_{CM}$	Pulsed Collector Current (Note 1)	120	A
$I_F$	Diode Continuous Forward Current ( $T_C=100^\circ C$ )	40	A
$I_{FM}$	Diode Maximum Forward Current (Note 1)	120	A
$P_D$	Maximum Power Dissipation ( $T_C=25^\circ C$ )	357	W
	Maximum Power Dissipation ( $T_C=100^\circ C$ )	179	W
$T_J$	Operating Junction Temperature Range	-40 to +175	$^\circ C$
$T_{STG}$	Storage Temperature Range	-40 to +175	$^\circ C$

### Thermal Characteristics

Symbol	Parameter	Max.	Units
$R_{thj-c}$	Thermal Resistance, Junction to case for IGBT	0.42	$^\circ C/W$
$R_{thj-c}$	Thermal Resistance, Junction to case for Diode	0.8	$^\circ C/W$
$R_{thj-a}$	Thermal Resistance, Junction to Ambient	40	$^\circ C/W$

## Electrical Characteristics ( $T_C=25^{\circ}\text{C}$ unless otherwise noted )

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$BV_{CES}$	Collector-Emitter Breakdown Voltage	$V_{GE}=0V, I_C=250\mu A$	1200	-	-	V
$I_{CES}$	Collector-Emitter Leakage Current	$V_{CE}=1200V, V_{GE}=0V$	-	-	100	$\mu A$
$I_{GES}$	Gate Leakage Current, Forward	$V_{GE}=\pm 30V, V_{CE}=0V$	-	-	$\pm 100$	nA
$V_{GE(th)}$	Gate Threshold Voltage	$V_{GE}=V_{CE}, I_C=250\mu A$	4.5	-	6.5	V
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$V_{GE}=15V, I_C=40A$	-	1.7	-	V
$Q_g$	Total Gate Charge	$V_{CC}=960V$ $V_{GE}=15V$ $I_C=40A$	-	252	-	nC
$Q_{ge}$	Gate-Emitter Charge		-	34.6	-	nC
$Q_{gc}$	Gate-Collector Charge		-	120	-	nC
$t_{d(on)}$	Turn-on Delay Time	$V_{CC}=600V$ $V_{GE}=15V$ $I_C=40A$ $R_G=15\Omega$ Inductive Load $T_C=25^{\circ}\text{C}$	-	72	-	ns
$t_r$	Turn-on Rise Time		-	66	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	450	-	ns
$t_f$	Turn-off Fall Time		-	43	-	ns
$E_{on}$	Turn-on Switching Loss		-	3.1	-	mJ
$E_{off}$	Turn-off Switching Loss		-	1.4	-	mJ
$E_{ts}$	Total Switching Loss		-	4.5	-	mJ
$C_{ies}$	Input Capacitance	$V_{CE}=25V$ $V_{GE}=0V$ $f=1\text{MHz}$	-	5052	-	pF
$C_{oes}$	Output Capacitance		-	115	-	pF
$C_{res}$	Reverse Transfer Capacitance		-	29	-	pF

## Electrical Characteristics of Diode ( $T_C=25^{\circ}\text{C}$ unless otherwise noted )

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_F$	Diode Forward Voltage	$I_F=40A$	-	2.0	3.2	V
$t_{rr}$	Diode Reverse Recovery Time	$V_{CE}=600V$ $I_F=40A$ $dI_F/dt=700A/\mu s$	-	340	-	ns
$I_{rr}$	Diode peak Reverse Recovery Current		-	21	-	A
$Q_{rr}$	Diode Reverse Recovery Charge		-	3050	-	nC

### Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature

## Typical Performance Characteristics

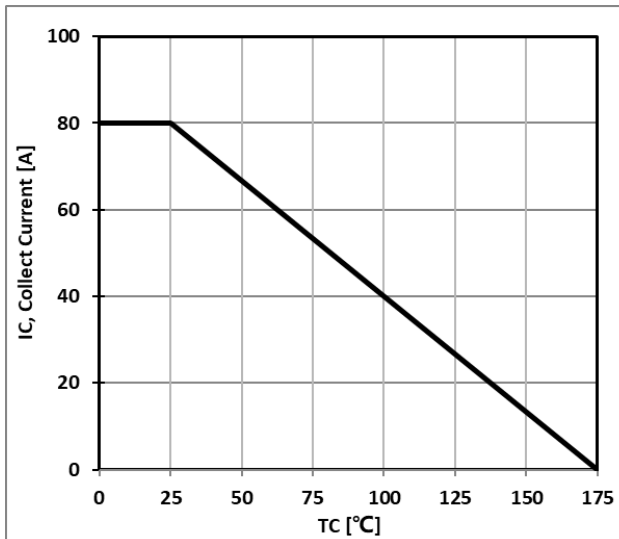


Figure 1: Maximum DC Collector Current  
VS. case temperature

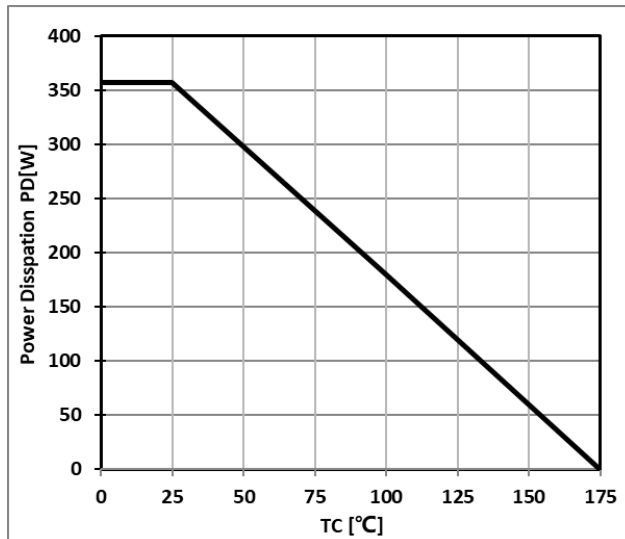


Figure 2: Power Dissipation VS. Case Temperature

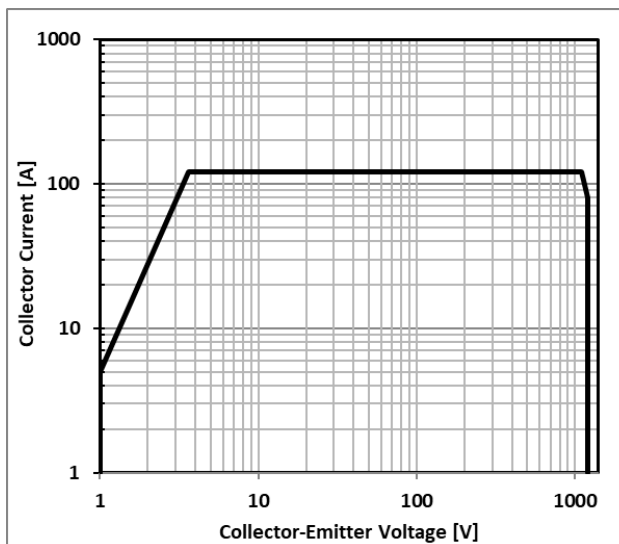


Figure 3: Reverse Bias SOA,  $T_J=125^{\circ}\text{C}$ ,  $V_{GE}=15\text{V}$

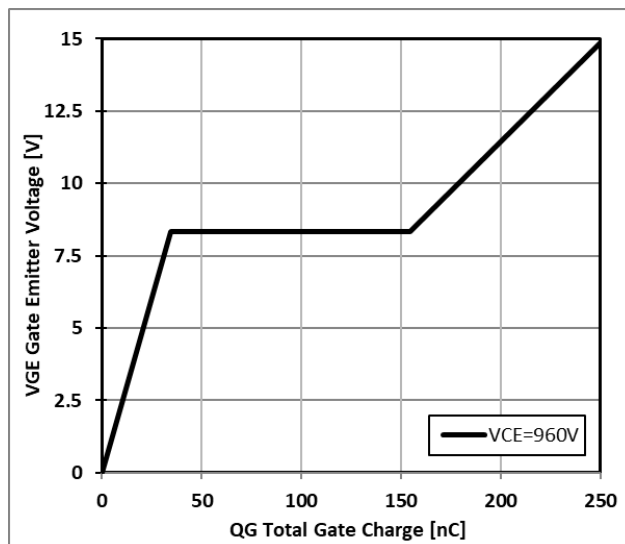


Figure 4: Typical Gate charge VS.  $V_{GE}$ ,  $I_C=40\text{A}$

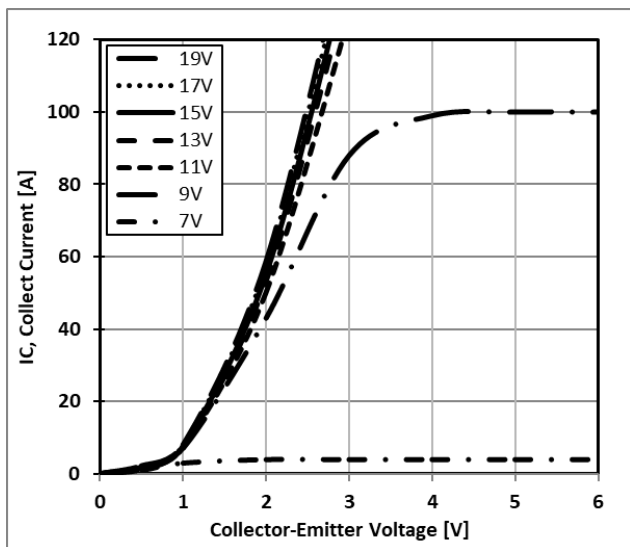


Figure 5: Typical IGBT Output characteristics,  
TC=25°C;tp=300us

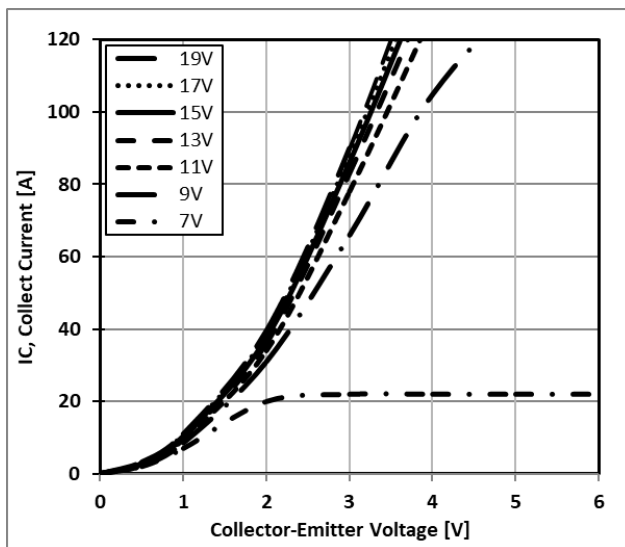


Figure 6: Typical IGBT Output characteristics,  
TC=150°C;tp=300us

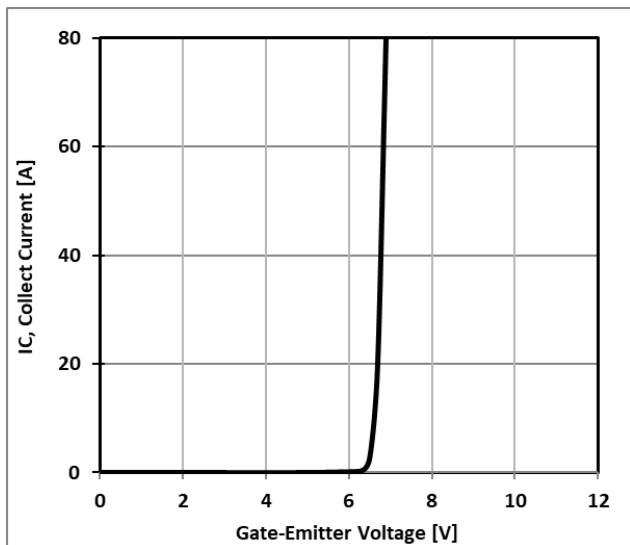


Figure 7: Typical Gate Threshold Voltage

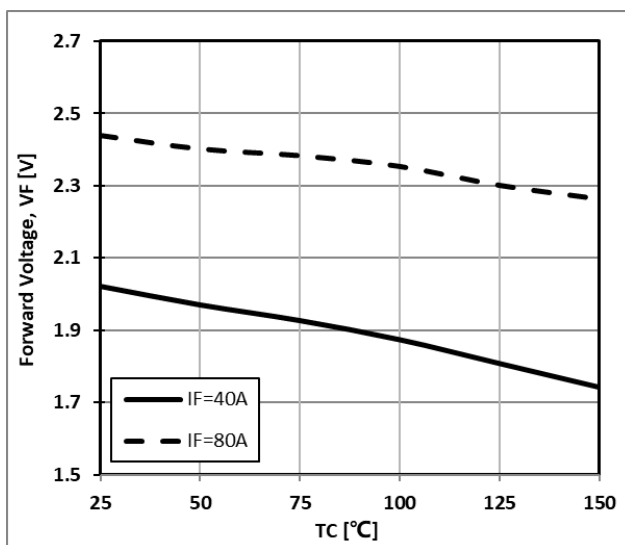


Figure 8: Typical Forward Voltage vs IF

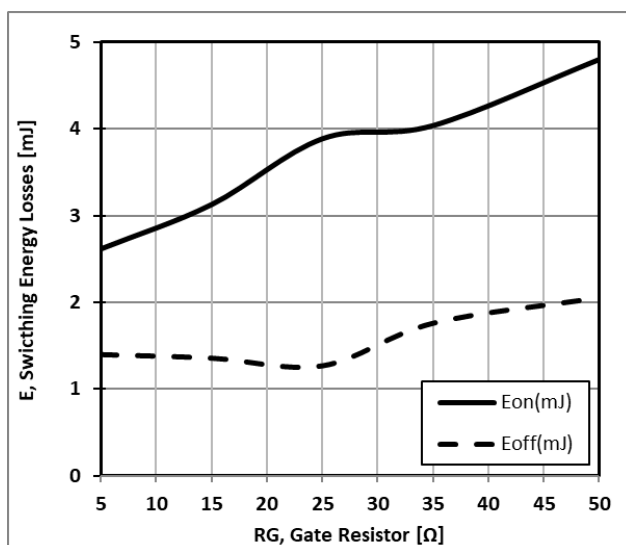


Figure 9: Typical Energy Loss VS. RG, TC=25°C,  
L=200uH, VCE=600V, VGE=15V, IC=40A

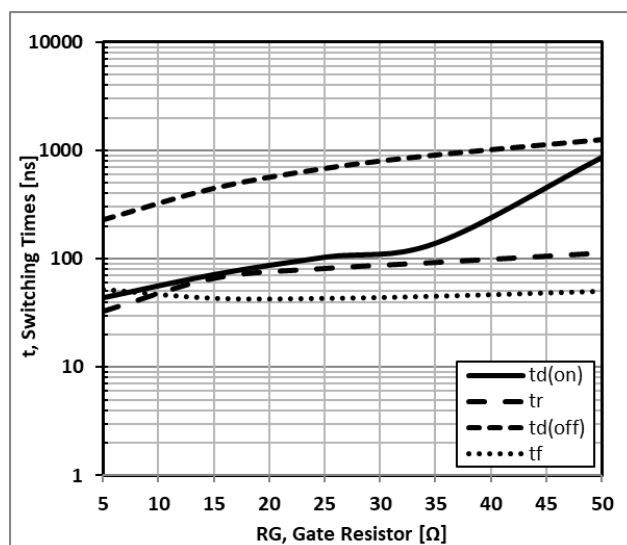


Figure 10: Typical Switching Time VS. RG, TC=25°C,  
L=200uH, VCE=600V, VGE=15V, IC=40A

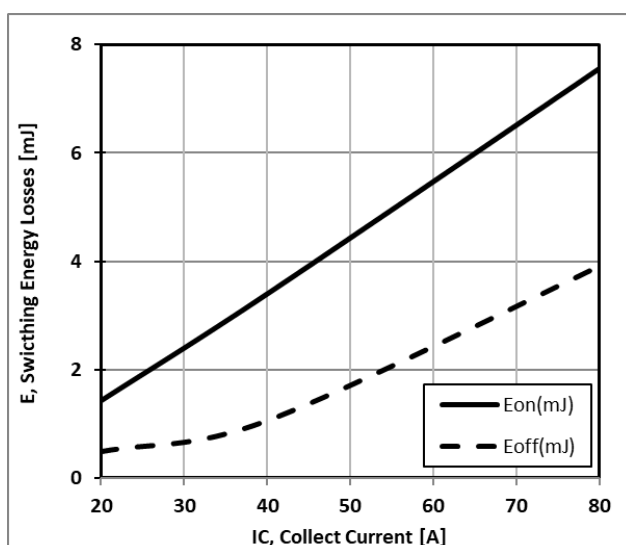


Figure 11: Typical Energy Loss VS. IC, TC=25°C,  
L=200uH, VCE=600V, VGE=15V, RG=15Ω

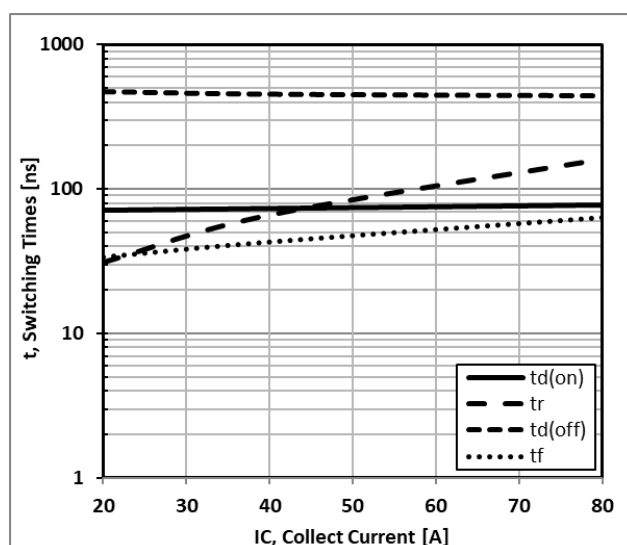


Figure 12: Typical Switching Time VS. IC, TC=25°C,  
L=200uH, VCE=600V, VGE=15V, RG=15Ω

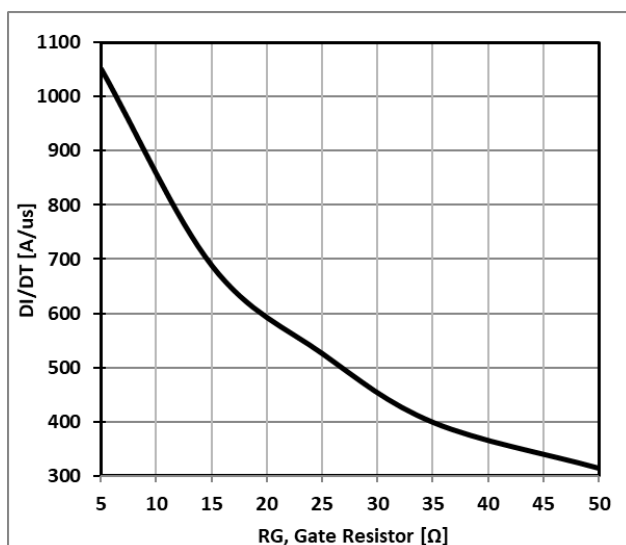


Figure 13: Typical Diode DI/DT VS. RG, TC=25°C  
VCC=600V, VGE=15V, IF=40A

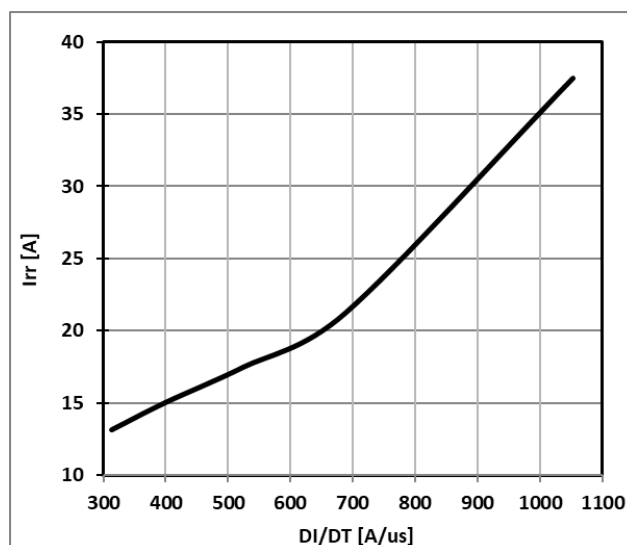


Figure 14: Typical Diode IRR VS. DI/DT, TC=25°C  
VCC=600V, VGE=15V, IF=40A

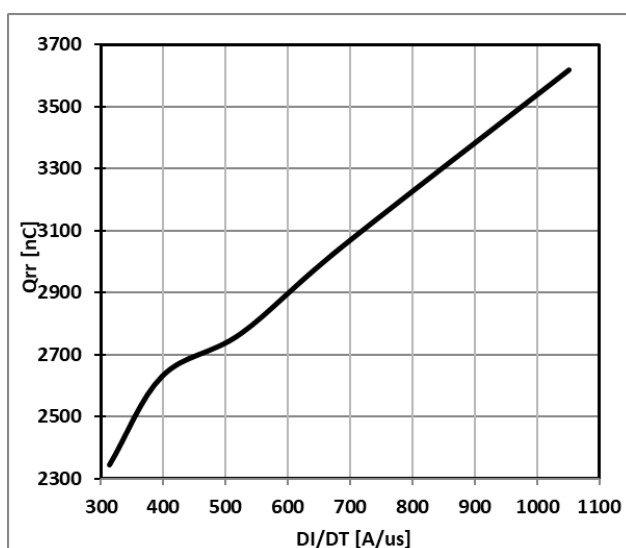


Figure 15: Typical Diode Qrr VS. DI/DT, TC=25°C  
VCC=600V, VGE=15V, IF=40A

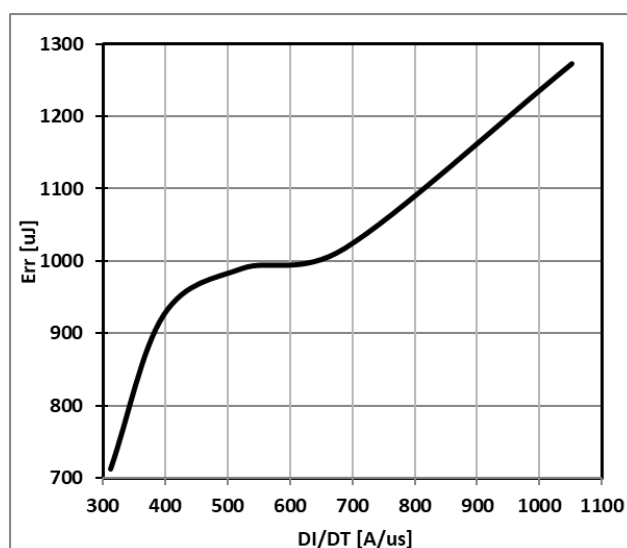


Figure 16: Typical Diode Err VS. DI/DT, TC=25°C  
VCC=600V, VGE=15V, IF=40A

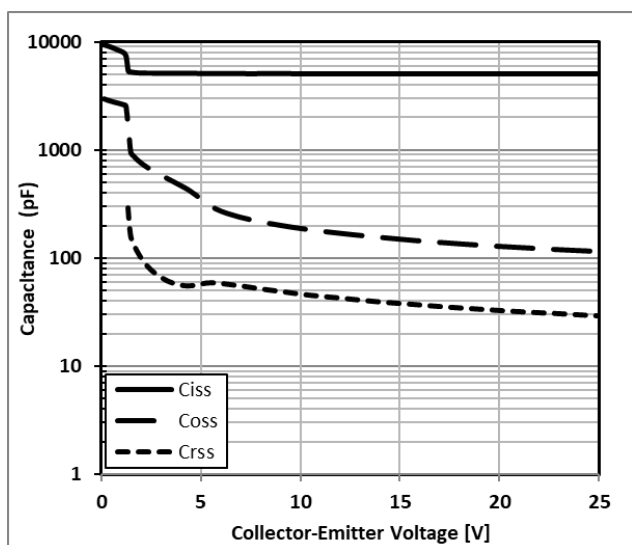


Figure 17: Typical Capacitance VS. VCE,  
VGE=0V, f=1MHz

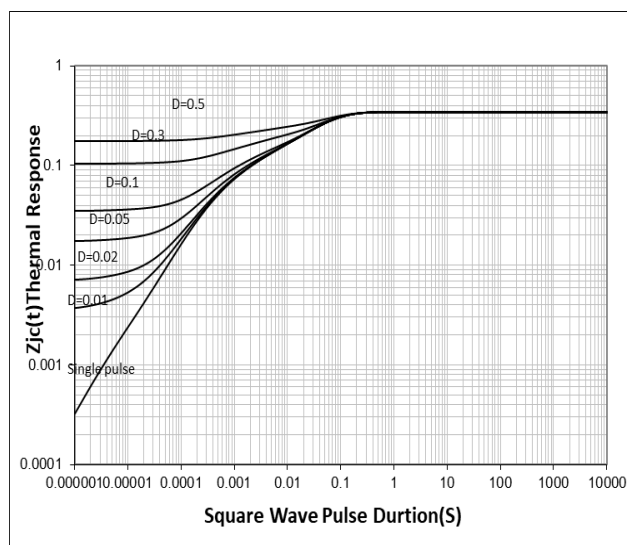
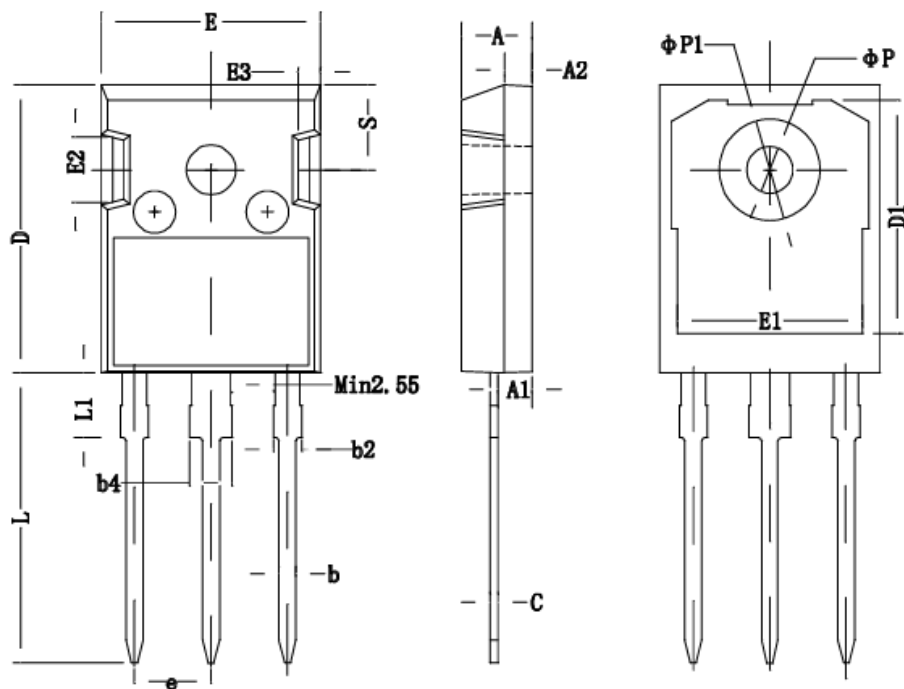


Figure 18: Normalized transient thermal impedance  
junction-to-case

## TO-247 PACKAGE OUTLINE



Symbol	mm		
	Min	Non	Max
A	4.80	5.00	5.20
A1	2.21	2.41	2.59
A2	1.85	2.00	2.15
b	1.11	1.21	1.36
b2	1.91	2.01	2.21
b4	2.91	3.01	3.21
c	0.51	0.61	0.75
D	20.80	21.00	21.30
D1	16.25	16.55	16.85
E	15.50	15.80	16.10
E1	13.00	13.30	13.60
E2	4.80	5.00	5.20
E3	2.30	2.50	2.70
e	5.44BSC		
L	19.82	19.92	20.22
L1	-	-	4.30
$\phi P$	3.40	3.60	3.80
$\phi P1$	-	-	7.30
S	6.15BSC		



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